

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	600	(chip or die) and semiconductor and substrate and (copper or cu) and ((underfill\$3 or filler \$3) same resin) and ((coefficient adj1 thermal adj1 expansion) or cte)	USPAT	OR	OFF	2009/01/01 17:22
L2	682	(chip or die) and semiconductor and substrate and (copper or cu) and ((underfill\$3 or filler \$3) same resin) and ((coefficient adj1 thermal adj1 expansion) or cte)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/01 17:57

1/ 1/ 09 6:13:58 PM

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EAST Workspace 1600x1200.wsp